RELIABILITY REPORT

FOR

MAX16001BTE+

PLASTIC ENCAPSULATED DEVICES

February 18, 2010

MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX16001BTE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX16000-MAX16007 are low-voltage, quad-/hex-/octal-voltage µP supervisors in small thin QFN and TSSOP packages. These devices provide supervisory functions for complex multivoltage systems. The MAX16000/MAX16001/MAX16002 monitor four voltages, the MAX16003/MAX16004/MAX16005 monitor six voltages, and the MAX16006/MAX16007 monitor eight voltages. The MAX16000/MAX16001/MAX16003/MAX16004/MAX16006 offer independent outputs for each monitored voltage. The MAX16001/MAX16002/MAX16004-MAX16007 offer a reset output that asserts whenever any of the monitored voltages fall below their respective thresholds or the manual reset input is asserted. The reset output remains asserted for the reset timeout after all voltages are above their respective thresholds and the manual reset input is deasserted. The minimum reset timeout is internally set to 140ms or can be adjusted with an external capacitor. All open-drain outputs have internal 30µA pullups that eliminate the need for external pullup resistors. However, each output can be driven with an external voltage up to 5.5V. Other features offered include a manual reset input, a tolerance pin for selecting 5% or 10% input thresholds, and a margin enable function for deasserting the outputs during margin testing. The MAX16001/MAX16002/MAX16004-MAX16007 offer a watchdog timer that asserts active-low RESET or an independent watchdog output (MAX16005) when the watchdog timeout period (1.6s typ) is exceeded. The watchdog timer can be disabled by floating the input. These devices are offered in 12-, 16-, 20-, and 24-lead thin QFN and 16-lead TSSOP packages. These are fully specified from -40°C to +125°C.

II. Manufacturing Information

A. Description/Function:	Low-Voltage, Quad-/Hex-/Octal-Voltage µP Supervisors in TQFN
B. Process:	B8
C. Number of Device Transistors:	3416
D. Fabrication Location:	California or Texas
E. Assembly Location:	China, Thailand
F. Date of Initial Production:	October 22, 2005

III. Packaging Information

A. Package Type:	16-pin TQFN 4x4
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2024
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	59.3°C/W
K. Single Layer Theta Jc:	5.7°C/W
L. Multi Layer Theta Ja:	40°C/W
M. Multi Layer Theta Jc:	5.7°C/W

IV. Die Information

A. Dimensions:	78 X 79 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 45 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 23.9 \times 10^{-9}$

$\lambda = 23.9$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The MS96 die type has been found to have all pins able to withstand a HBM transient pulse of 2500 per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of 250.

Table 1

Reliability Evaluation Test Results

MAX16001BTE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data